

PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

EPAS ID: PAT8413249

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
DEFOND COMPONENTS LIMITED	03/13/2019
RECEIVING PARTY DATA	
Name:	DEFOND ELECTECH CO. LTD.
Street Address:	HONGMEI SECOND INDUSTRIAL AREA
Internal Address:	HONGMEI TOWN
City:	DONGGUAN GUANGDONG
State/Country:	CHINA
Postal Code:	523160
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	18119054
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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ATTORNEY DOCKET NUMBER:	270091.403C1/00574530
NAME OF SUBMITTER:	FRANK ABRAMONTE
SIGNATURE:	/Frank Abramonte/
DATE SIGNED:	01/31/2024
Total Attachments: 3	
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ASSIGNMENT

WHEREAS, DEFOND COMPONENTS LIMITED, a Hong Kong company, having its principal place of business in Chai Wan, Hong Kong, owns certain inventions entitled "A CONTROL ASSEMBLY FOR USE IN OPERATION OF AN ELECTRIC DEVICE" ("the Invention"), for which an application for United States letters patent was filed on November 5, 2018, and assigned Application No. 16/180,922; which claims priority to Hong Kong Short Term Patent Application No. 17111877.6, filed November 15, 2017; and

WHEREAS, DEFOND ELECTECH CO., LTD., a Chinese company, having its principal place of business in Guangdong, China, is desirous of acquiring an interest therein;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which hereby are acknowledged, DEFOND COMPONENTS LIMITED sells, assigns, and transfers to DEFOND ELECTECH CO., LTD., its successors and assigns, a 50% equal share of all rights to the Inventions in the United States and its territorial possessions and in all foreign countries, and a 50% equal share of all rights, title, and interest in and to any and all Patents that may be granted therefor in the United States and its territorial possessions and in any and all foreign countries, and in and to any and all subsequent, related provisional applications, U.S. non-provisional applications, divisions, continuations, reissues, substitutions, and extensions thereof.

DEFOND COMPONENTS LIMITED hereby authorizes and requests the Patent Office officials in the United States and any and all foreign countries to issue any and all of the Patents, when granted, to DEFOND ELECTECH CO., LTD., as the co-applicant/co-assignee of its equal rights, title, and interest in and to the same, for the use of DEFOND ELECTECH CO., LTD., its successors and assigns.

Further, DEFOND COMPONENTS LIMITED hereby covenants and agrees to and with DEFOND ELECTECH CO., LTD., and its successors and assigns, at the time of execution and delivery of the Inventions, that DEFOND COMPONENTS LIMITED is the sole and lawful owner of the entire right, title, and interest in and to the Inventions and the above-identified patent applications, that the same are unencumbered, and that it has good and full right and lawful authority to sell and convey the same in the manner herein set forth.

Further, DEFOND COMPONENTS LIMITED agrees that it will communicate to DEFOND ELECTECH CO., LTD., or its representatives, any facts known to it respecting the inventions, and testify in any legal proceedings, sign all lawful papers, execute all subsequent, related provisional, U.S. non-provisional, divisional, continuation, reissue, substitution, and extension applications, execute all necessary assignment papers to cause any and all of the Patents to be issued naming DEFOND ELECTECH CO., LTD. as a co-applicant/co-assignee, make all rightful oaths, and generally do everything possible to aid DEFOND ELECTECH CO., LTD., and its successors and assigns, to obtain and enforce proper protection for the Inventions in the United States and in any and all foreign countries.

DEFOND COMPONENTS LIMITED

Dated: 13 MAR 2019



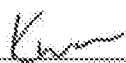
Name: RICHARD OR

Title: CEO

Date 13 MAR 2019

Signed at Hong Kong

SAMSON KUAN
(Name of Witness)


(Signature of Witness)

DEFOND ELECTRON CO., LTD.

Dated: 13 MAR 2019



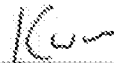
Name: RICHARD OR

Title: CEO

Date 13 MAR 2019

Signed at Hong Kong

SAMSON KWAN
(Name of Witness)


(Signature of Witness)